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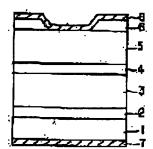
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(54) COMPOUND SEMICONDUCTOR ELEMENT

(57)Abstract:

PURPOSE: To accomplish high efficiency of a semiconductor element by providing a cubic crystal SiC substrate and a GaxAlxIn1-x-yN (0≤x≤1, 0≤y≤1) layer. CONSTITUTION: A GaN buffer layer 2 of 1 µm in thickness, a clad layer 3 consisting of p-GaAlInN of 1 µm in thickness, a light-emitting layer 4 consisting of undoped GaAlInN of 0.1 µm in thickness, are formed successively on a 3C-SiC substrate 1, and a semiconductor layer is composed of the abovementioned layers. As the clad layer 5, consisted of final GaAllnN, is formed in N-type in this semiconductor laser, the taking-in of hydrogen into the p-GaAllnN clad layer 3 can be prevented, and a low resistance p-GaAlinN clad layer 3 can be formed. As a result, a high brightness short wavelength light-emitting element can be obtained.



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